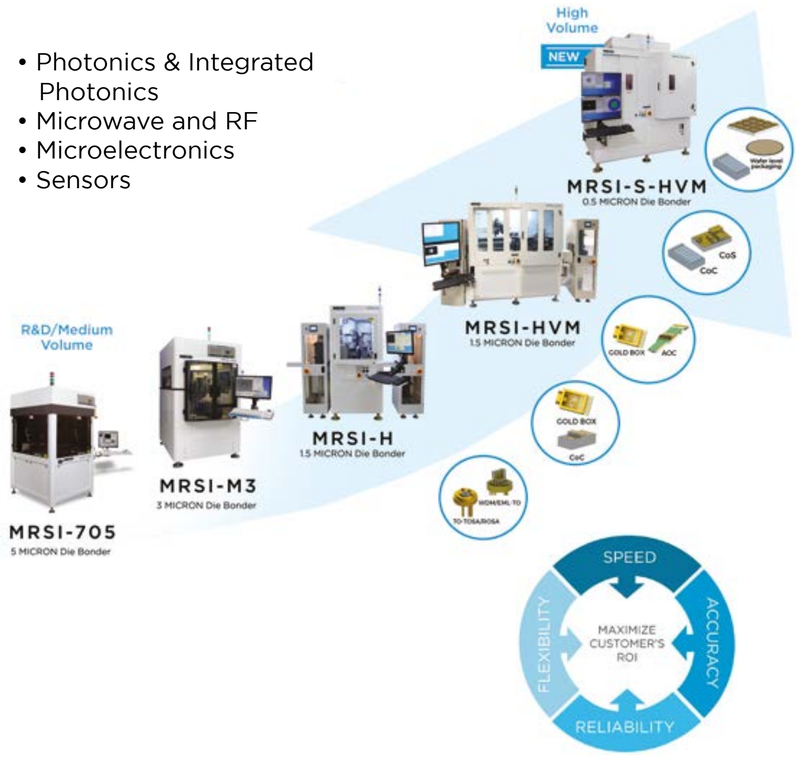
DIE BONDING AND DISPENSING SOLUTIONS

COMPLETE LINE OF SOLUTIONS

- Photonics & Integrated Photonics
- Microwave and RF
- Microelectronics
- Sensors



SCALE WITH US

MRSI Systems & US Demo Center
554 Clark Rd
Tewksbury, MA 01876 USA
Tel: +1 978 667 9449
www.mrsisystems.com

MRSI China Demo Center
101, Block A, HUAHAN Innovation Park Office Bldg.
Langshan Road, Nashan District, Shenzhen,
518000 P. R. China
Tel: +86-755-26414155

MRSI Systems (Mycronic Group), is the leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. We offer solutions for research and development, low-to-medium volume production, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, AOCs, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, and optical imaging products. With 30+ years of industry experience and our worldwide local technical support team, we provide the most effective systems and assembly solutions for all packaging levels including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. For more information visit www.mrsisystems.com.

Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic headquarters is located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Singapore, South Korea, the Netherlands, United Kingdom and the United States. Mycronic (MYCR) is listed at Nasdaq Stockholm. www.mycronic.com

Specifications are subject to change without notice.

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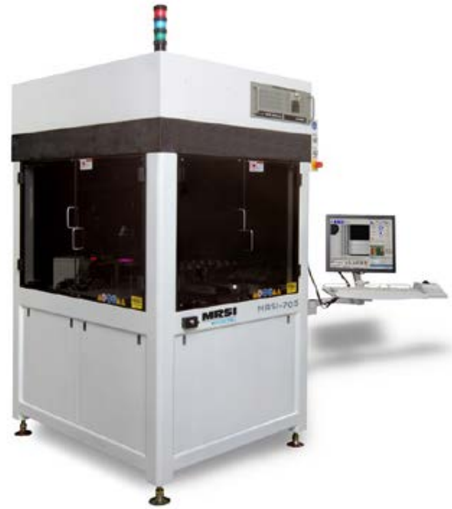
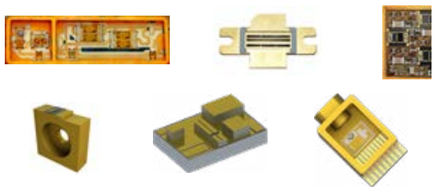
MRSI-705 Die Bonder



"All-In-One" Platform
Ultimate Flexibility
5 MICRON

MRSI MYCRONIC



MRSI Systems has been serving optoelectronic and microelectronic customers for the past 35 years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications are found across a wide range of market segments, such as life & health sciences, aerospace, defense, automotive, lighting, communications, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-pace innovations of critical components for high-growth market segments. The ultra-flexible MRSI-705 can be used for research and development prototyping to low/medium volume and with our optional Turret configuration high volume can be achieved.

Our family of die bonding solutions are built with the same hardware and software platforms configured to minimize process deviations, reduce NPI cost, and increase ROI for customers with MRSI's long proven product reliability and global customer support.

MRSI-705
Ultimate flexibility

Assembly Technologies

- Eutectic Bonding
- Epoxy Die Attach
- In-situ UV Bonding
- Flip Chip Assembly
- Thermal Compression Bonding

"All-in-one" Platform

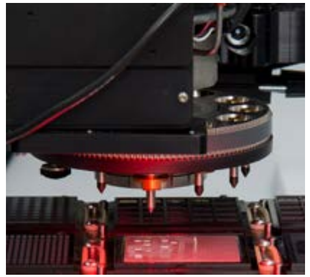
- Large Configurable Work Area
- Force Control for Advanced Assembly
- Advanced Machine Vision
- Programmable Multi-Color Lighting
- Quality Software, Computer and Motion Control
- Turnkey Integrated Production Lines

Configuration for Higher Speed & Volume

The MRSI-705 offers an optional Turret configuration to significantly increase the speed and potential volume from our machine without sacrificing flexibility. This feature delivers an "on-the-fly" tool change with up to 12 tools with zero tool changeover downtime.

This leads to increased machine efficiency, higher output and lower manufacturing costs.

Applications include processes requiring a large number of parts-specific tools, using eutectic bonding, and the need to assemble complex products with a multitude of component types.



Applications

- 3D Packaging
- Wafer Scale Packaging
- LED Assembly
- Microwave Modules
- Photonics Packaging
- RF Power Amplifiers
- Infrared Sensors
- Pressure Sensors
- MEMS Devices
- Semiconductor Packaging
- Hybrid Circuits
- Multichip Modules
- Pacemakers and Hearing Aids
- Medical Imaging
- Laser Diode Bonding
- Inkjet and Print Head
- System on a Chip
- System in a Package